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AN 2000:227570 HCAPLUS
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TI Solder for electric, electronic, audio and video devices
IN Yamaguchi, Atsushi; Hirano, Masato; Suetsugu, Kenichiro; Nakata, Mikiya
PA Matsushita Electric Industrial Co., Ltd., Japan
SO PCT Int. Appl., 45 pp.
CODEN: PIXXD2

DT Patent
LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	WO 2000018536	A1	20000406	WO 1999-JP5244	19990924
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	RW: AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE				
	JP 2000173253	A2	20000623	JP 1999-272264	19990927
PRAI	JP 1998-279211	A	19980930		
AB	A solder for elec., electronic, audio and video devices is from an alloy contg. Sn and Ag as essential components and .gtoreq.1 of Bi, In and Cu . The solder provides for excellent heat and impact resistance.				
RE.CNT	19	THERE ARE 19 CITED REFERENCES AVAILABLE FOR THIS RECORD			
		ALL CITATIONS AVAILABLE IN THE RE FORMAT			